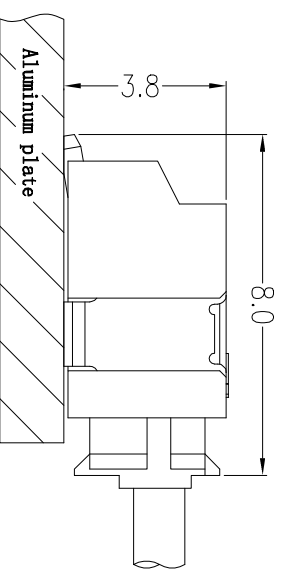
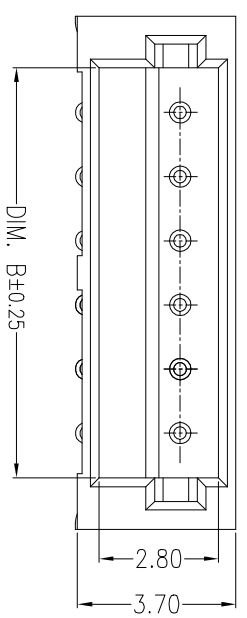
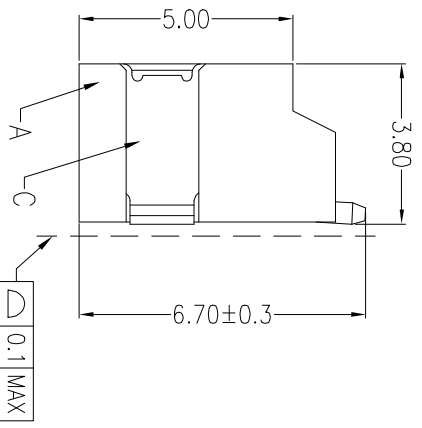
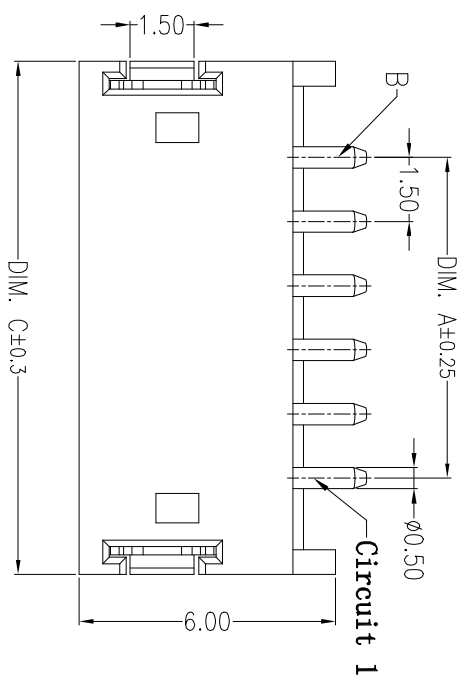


REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
C		调整接触点螺距规格	2021.10.22	XUETAOCUO

NOTE:  
 1. MATERIAL: SEE BOM  
 2. NICKLE 50U" Min UNDERPLATING OVER ALL.  
 3. SPEC. PLS. REFER TO EIO34:  
 DIM. MARKED  $\otimes$  SHOULD BE MEASURED BY FAI;  
 DIM. MARKED  $\nabla$  SHOULD BE CONTROLLED BY QC;  
 DIM. MARKED  $\square$  SHOULD BE MEASURED TERMLY BY QC;  
 DIM. MARKED  $\square$  SHOULD BE ANALYSED TERMLY BY QC;

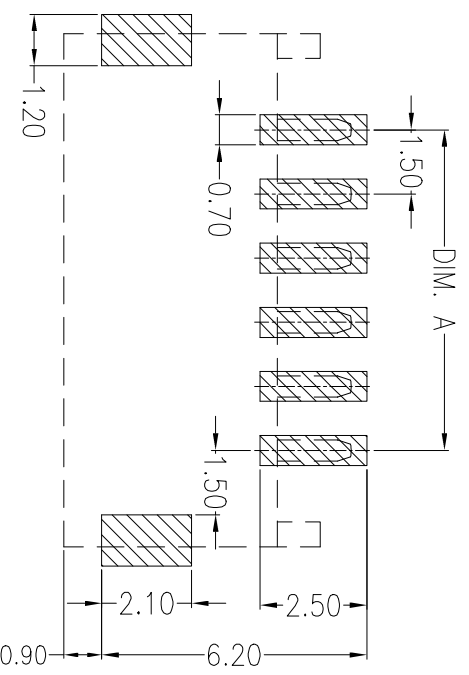
4. ORDERING INFORMATION:

WB1519 H- XX X X X  
 WITHOUT "H": WITH HALOGEN PIN  
 WITH "H": HALOGEN FREE NO.  
 PACKING:  
 O: TAPE&REEL  
 1: TUBE  
 X: BLACK  
 N: NATURAL  
 PLATING SPEC  
 S: MATT Sn  
 G: GOLD FLASH  
 T: GOLD 3U" ON CONTACT AREA

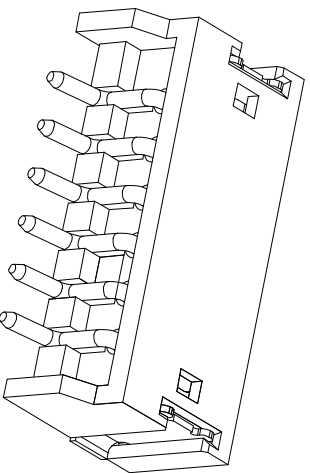


Assembly Layout

Circuits	Dimensions (mm)		
	DIM. A	DIM. B	DIM. C
02	1.50	3.60	6.00
03	3.00	5.10	7.50
04	4.50	6.60	9.00
05	6.00	8.10	10.50
06	7.50	9.60	12.00
07	9.00	11.10	13.50
08	10.50	12.60	15.00
09	12.00	14.10	16.50
10	13.50	15.60	18.00
11	15.00	17.10	19.50
12	16.50	18.60	21.00
13	18.00	20.10	22.50
14	19.50	21.60	24.00
15	21.00	23.10	25.50
16	22.50	24.60	27.00



SUGGESTED PCB LAYOUT



3	NAIL	2	COPPER ALLOY
2	TERMINAL	~	BRASS
1	HOUSING	1	THERMOPLASTIC UL94-V0
NO.	DESCRIPTION	Q'TY.	MATERIAL
<p>一般公差            TOLERANCES            X: ±0.5            .XX ±0.15            .X ±0.25            .XXX ±0.1            ANGLES ±2°</p>			
<p>繪圖尺寸標示            SYMBOLS <math>\otimes</math> INDICATE CLASSIFICATION DIMENSION            MARK IS CRITICAL DIM.            MARK IS MAJOR DIM.            表面處理 (FINISH)</p>			
品名 (TITLE)		製圖 (DR)	
1.5mm PITCH 90WATER SMT TYPE		XUETAOCUO	
圖號 (ONG NO.)		審核 (CHK)	
C-WB1519H-XXXXX		LEO-HE	
比例 (SCALE)		核准 (APP)	
5:1		LEO-HE	
單位 (UNITS)		張數 (SHEET)	
mm		1 OF 1	
圖號		SIZE	
A4		REV	
C			

希爾盛精密电子(昆山)有限公司